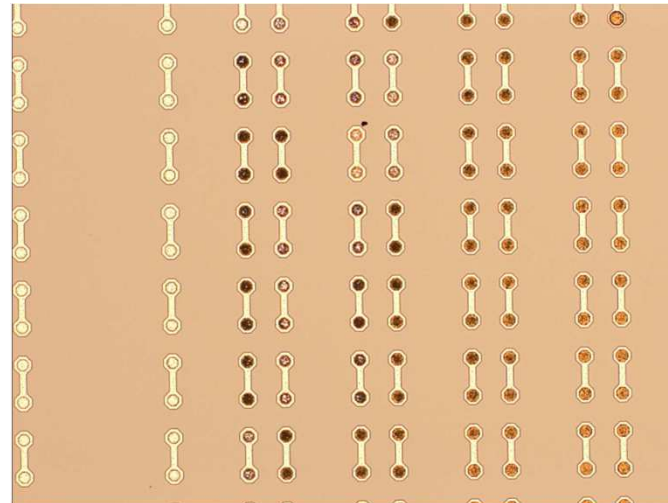


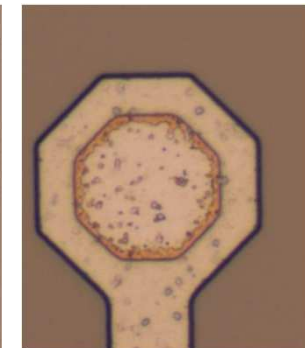
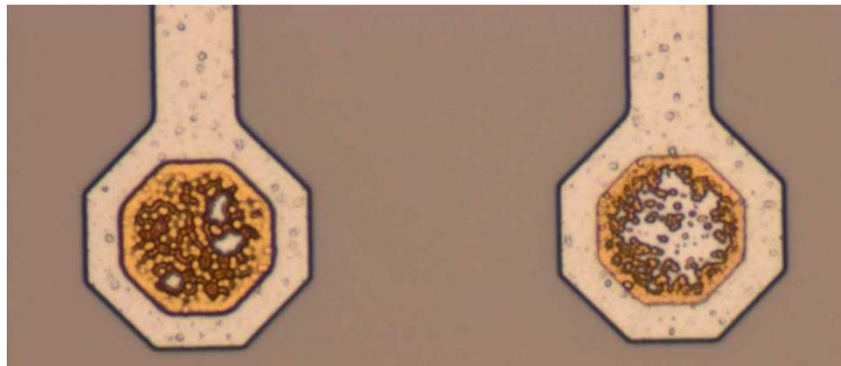
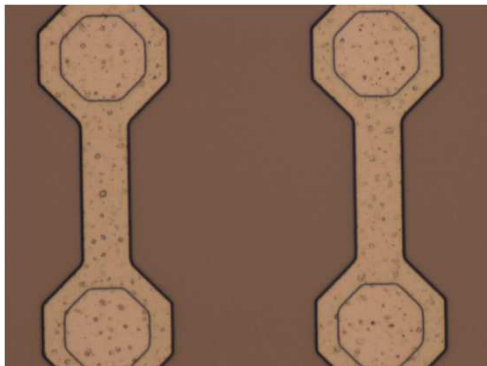
Pac Tech's electroless nickel gold (ENIG) UBM process failed on 5 of 7 CiS dummy wafers

OPTICAL MICROSCOPE PICTURES OF AFFECTED WAFERS

- First 7 AlSiCu wafers processed
- 2 wafers without failures
- 5 wafers show errors in UBM
- 12 unprocessed wafers (9 AlSiCu and 3 AlSi) go back to CiS



Overview
after ENIG
process



Zoomed views to pads either with missing or partial UBM after processing